

## SOD-523 贴片塑封二极管 SOD-523 Plastic-Encapsulate Diodes

### 特征 Features

- 平面工艺芯片结构 Planar Die Construction
- 功耗150毫瓦 150mW Power Dissipation
- 稳压值范围从5.1到20V Zener Voltages From 5.1 – 20V

### 机械数据 Mechanical Data

- 封装: SOD-523 封装 SOD-523 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

**Maximum Ratings & Thermal Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
正向电压 Forward Voltage @IF=10mA	V <sub>F</sub>	0.9	V
功率消耗 Power Dissipation (Note 1)	P <sub>d</sub>	150	mW
结温 Junction temperature	T <sub>j</sub>	150	°C
存储温度 Storage temperature range	T <sub>STG</sub>	-55-+150	°C
热阻 Thermal Resistance from Junction to Ambient	R <sub>θJA</sub>	833	°C/W

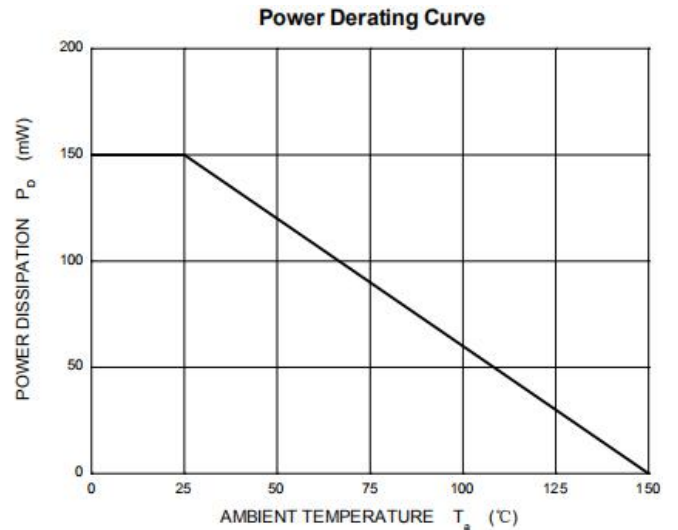
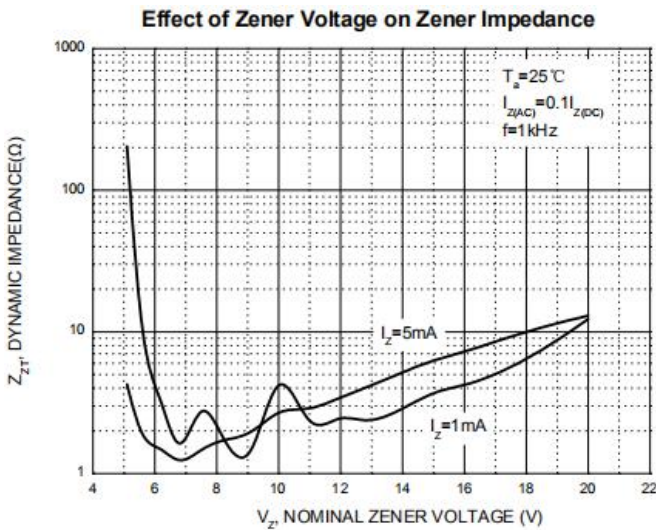
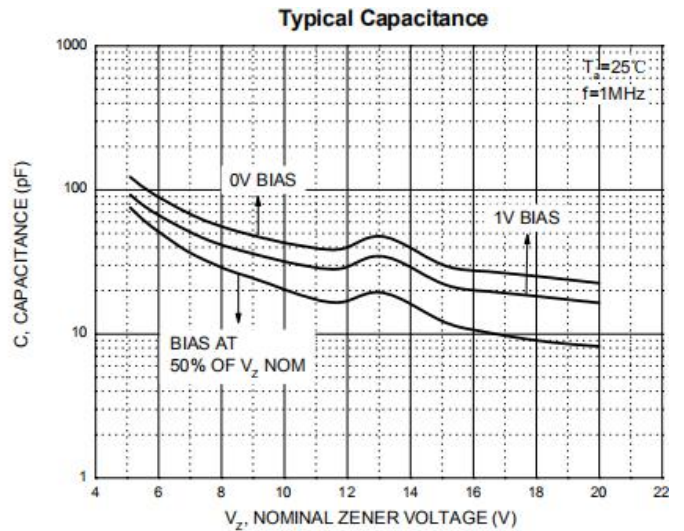
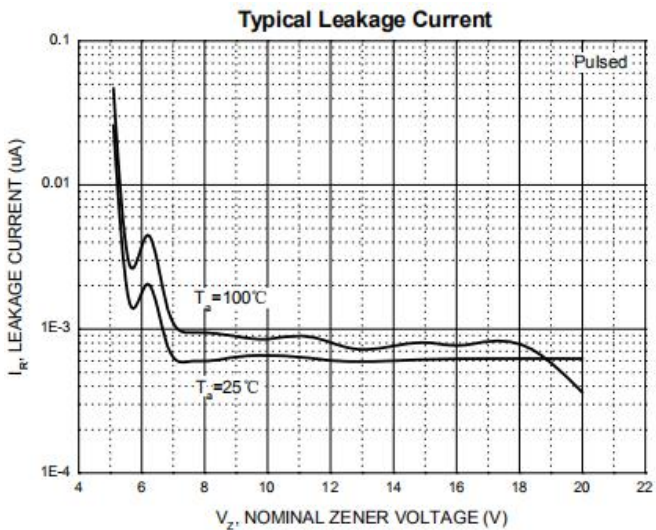
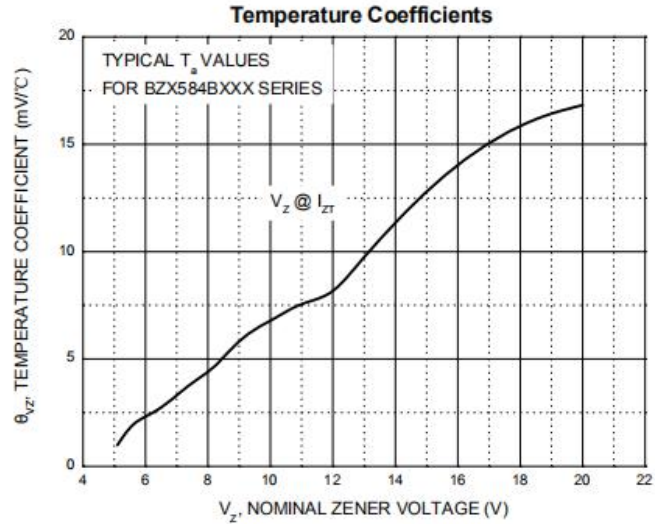
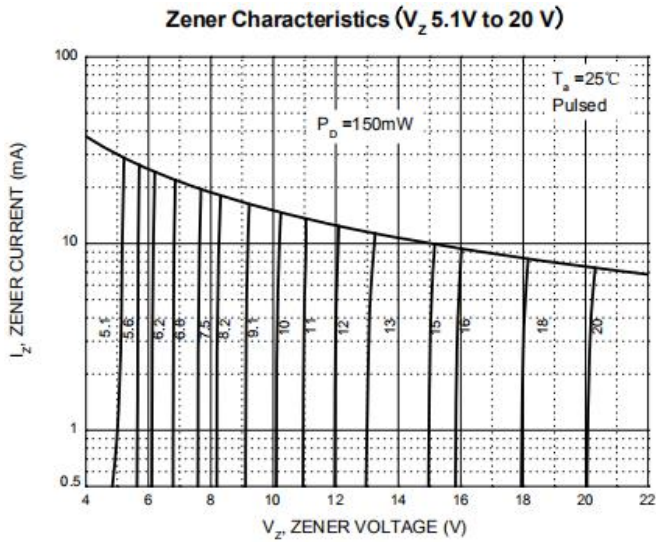
电特性 **Electrical Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified.)

Type Number	Type Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current		Typical Temperature Coefficient @I <sub>ZT</sub> =5 mA mV/°C	
		V <sub>Z</sub> @I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	V <sub>R</sub>	Min	Max
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	μA	V		
BZX584B5V1	2Z2	5.1	5.00	5.20	5	60	480	1.0	2	2.0	-2.7	1.2
BZX584B5V6	2Z3	5.6	5.49	5.71	5	40	400	1.0	1	2.0	-2.0	2.5
BZX584B6V2	2Z4	6.2	6.08	6.32	5	10	150	1.0	3	4.0	0.4	3.7
BZX584B6V8	2Z5	6.8	6.66	6.94	5	15	80	1.0	2	4.0	1.2	4.5
BZX584B7V5	2Z6	7.5	7.35	7.65	5	15	80	1.0	1	5.0	2.5	5.3
BZX584B8V2	2Z7	8.2	8.04	8.36	5	15	80	1.0	0.7	5.0	3.2	6.2
BZX584B9V1	2Z8	9.1	8.92	9.28	5	15	100	1.0	0.5	6.0	3.8	7.0
BZX584B10	2Z9	10	9.80	10.20	5	20	150	1.0	0.2	7.0	4.5	8.0
BZX584B11	2Y1	11	10.78	11.22	5	20	150	1.0	0.1	8.0	5.4	9.0
BZX584B12	2Y2	12	11.76	12.24	5	25	150	1.0	0.1	8.0	6.0	10.0
BZX584B13	2Y3	13	12.74	13.26	5	30	170	1.0	0.1	8.0	7.0	11.0
BZX584B15	2Y4	15	14.70	15.30	5	30	200	1.0	0.1	10.5	9.2	13.0
BZX584B16	2Y5	16	15.68	16.32	5	40	200	1.0	0.1	11.2	10.4	14.0
BZX584B18	2Y6	18	17.64	18.36	5	45	225	1.0	0.1	12.6	12.4	16.0
BZX584B20	2Y7	20	19.60	20.40	5	55	225	1.0	0.1	14.0	14.4	18.0

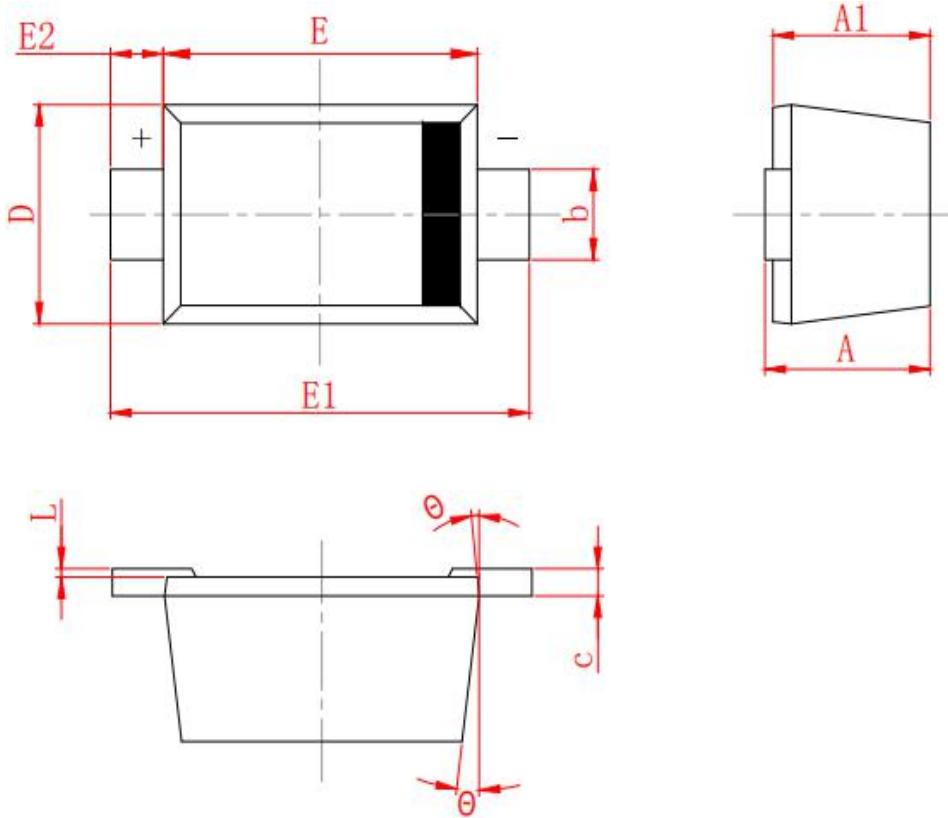
Notes:

1. Valid provided that device terminals are kept at ambient temperature.
2. Tested with pulses, period=5ms,pulse width =300μs.
3. f=1kHz.

典型特性 Typical Characteristics

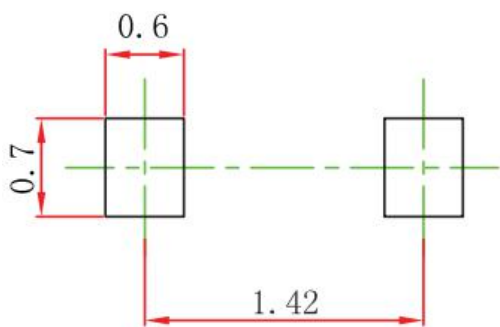


SOD-523封装外形尺寸图 SOD-523 Package Outline Dimensions



SYMBOL	MILLIMETER	
	MIN	MAX
A	0.530	0.730
A1	0.500	0.700
b	0.280	0.380
c	0.080	0.150
D	0.750	0.850
E	1.100	1.300
E1	1.500	1.700
E2	0.200 REF	
L	0.010	0.070
θ	7° REF	

SOD-523焊盘设计参考 SOD-523 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.